

ABSTRACT

It is the object of the invention to provide a method for manufacturing a semiconductor chip capable of obtaining
5 a semiconductor chip at a high manufacturing efficiency without damages.

The invention is a method for manufacturing a semiconductor chip, which comprises a tape adhesion step of sticking a pressure sensitive adhesive tape for dicing
10 having a pressure sensitive adhesive layer containing a gas generating agent for generating a gas by radiating light to a semiconductor wafer with a circuit formed; a dicing step for dicing the wafer with the pressure sensitive adhesive tape for dicing stuck and dividing the semiconductor wafer
15 into each semiconductor chip; a separation step of separating at least a portion of the pressure sensitive adhesive tape for dicing from the semiconductor chip by radiating light to the divided each semiconductor chip; and a pickup step of picking the semiconductor chip up by a
20 needle-less pickup method.